

Data sheet Product ICK PGA 20 x 20 x 10



Heatsinks and active heatsinks for processors>Heatsinks for PGA

50 x 50 x 10 mm, for IC design PGA and others

Features

way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	50 mm
height:	10 mm
plate thickness:	2.5 mm
length:	50 mm
thermal resistance:	8.5 - 2.2 K/W
dissipation loss:	15.1 W
surface:	black anodised

Technical Drawing

